

Data and Facts

2014

SMT Assembly

Maximum output:	1500 million assemblies p. a.
Minimum assembly dimensions:	Type 0201
Maximum assembly dimensions:	55 mm ²
Fine pitch placement:	To 0.3 mm
Circuit board dimensions:	Max. 610 mm x 460 mm

Reflow:

- Vapour phase reflow
- Convection reflow

All fully automated reflow processes performed in a controlled nitrogen atmosphere (protective gas) and are available as leaded and unleaded processes.

THT Assembly

Maximum assembly output:	80 million assemblies p. a.
Automated assembly preparation	
Semi-automatic assembly with laser assembly benches	
Double wave soldering	
Selective soldering	
Board dimensions:	Max. 650 mm x 450/500 mm

All fully automated soldering processes performed in a controlled nitrogen atmosphere (protective gas) and are available as leaded and unleaded processes.

PCB Protection

Selective coating systems with conveyor oven	400 mm x 500 mm
Fully automated PCB encapsulation ("Macromelt") using hot melt moulding technology	

Cable Assembly

Fully automated single strand production	
Semi-automatic cable production	
IDC technology	
Crimping technology	
Soldering technology	
Semi and fully automated adhesive and encapsulation technology	

Testing

▪ In-circuit-testing	▪ Fully automated X-ray testing
▪ Functional testing	▪ Automatic visual inspection
▪ Climatic testing	▪ Combined testing
▪ Burn-In testing	▪ Safety category testing
▪ Run-In testing	▪ Custom testing
▪ High voltage testing	▪ Polished section analysis for soldered and crimp connections
▪ Cable testers	
▪ Sequential manufacturing testing system	

Certification

▪ ISO 9001	▪ EN ISO 13485
▪ DIN EN ISO 14001	▪ ISO/TS-16949

Good partnership counts

Good, reliable partners and suppliers are key factors that help us to maintain our competitive edge. Here is a selection of our partners in the field of machinery and equipment:

